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(54) Title: PACKAGED ELECTRONIC MODULE AND MANUFACTURING METHOD THEREOF

(57) Abstract: The present invention is a packaged electronic module with embedded electronics for use in smart cards. This invention assembles a plurality of electronics components on a flexible printed circuit, together with an integrated circuit chip and a contact plate, into a module. This module can then be embedded into a plastic card, using regular milling techniques, by a card manufacturer. This method packages the plurality of electronics components into a module. The present invention provides a business with the capability to avoid additional capital expenditure required for special equipment and enables all existing card manufacturers to manufacture smart cards with embedded electronics.



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